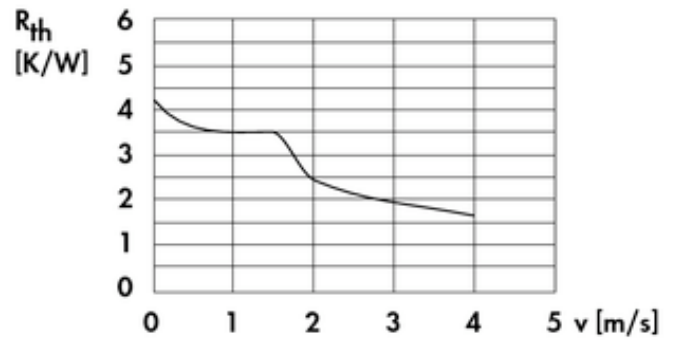
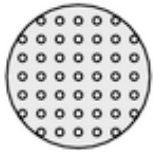
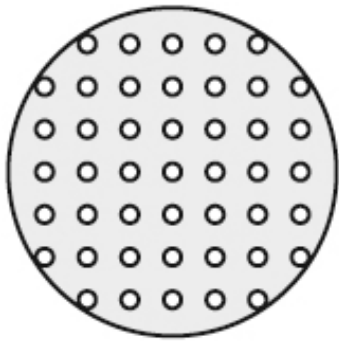


Pin heatsinks / **ICK S R 28,5 x 18,5**

Ø 28,5 x 18,5 mm, pin heatsinks round

Parameters of article ICK S R 28,5 x 18,5

Bauform	Rund
R_{th} [K/W]	4.25
dissipation loss [W]	20.2
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
Ø [mm]	28.5
height [mm]	18.5
plate thickness [mm]	3
weight [g]	6.98

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 D 28,5**

Thermally conductive foil both sides adhesive / **WLFT 405 D 28,5**